	Тур	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L20	1370	(257/690).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/05 11:11
2	BRS	L17	6	chips or device or devices)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/05 11:11
3	IS&R	L19	1398	(257/786), CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/05 11:12
4	BRS	L21	75	19 and (test\$3 near2 pad\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/05 11:31
5	BRS	L22	25	20 and (test\$3 near2 pad\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/05 11:31

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	Type	L #	Hits	Search T xt	DBs	Time Stamp
6	IS&R	L23	479	(257/620).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/05 12:08
7	BRS	L24	2	(die or dice or chip or chips or circuit\$4) same active same (test\$4 near2 pad\$3) same (input near2 bond\$4 near2 pad\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/05 13:06
8	BRS	L25	176	conduct\$4 with (bond\$4 near2 pad\$4) with (test\$4 near2 pad\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/05 13:59
9	IS&R	L26	1	("6522018").PN.		2003/08/05 14:22
10	BRS	L27	1	"input bond pad" with "test pad"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/05 14:23
11	BRS	L28	64	"bond pad" with "test pad"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/05 14:24

تمع

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